

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS
Total Drawing Sheets : 7
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 500077.12 (29222/US/11)
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a : divisional of
>Application One : 10/300,344
Filing Date : November 19, 2002
which is a : divisional of
>>Application Two : 09/854,390
Filing Date : May 11, 2001
Patent Number : 6,638,148
which is a : continuation of
>>>Application Three : 09/164,915
Filing Date : October 1, 1998
Patent Number : 6,250,994

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